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(71) Applicant *(for all designated States except US)*: **MICRON TECHNOLOGY INC.** [US/US]; 8000 South Federal Way, P.O. Box 6, Boise, Idaho 83707-0006 (US).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **WOOD, Alan, G.** [US/US]; 1366 E. Versailles Court, Boise, Idaho 83706 (US). **HIATT, William, M.** [US/US]; 1137 West Stafford Drive, Eagle, Idaho 83616 (US). **HEMBREE, David, R.** [US/US]; 11074 W. Edgehill Drive, Boise, Idaho 83709 (US).

(74) Agents: **GRATTON, Stephen, A.** et al.; 2764 South Braun Way, Lakewood, Colorado 80228 (US).

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(54) Title: BACKSIDE METHOD AND SYSTEM FOR FABRICATING SEMICONDUCTOR COMPONENTS WITH CONDUCTIVE INTERCONNECTS

(57) Abstract: A backside method for fabricating a semiconductor component (50) with a conductive interconnect (44) includes the step of providing a semiconductor substrate (12) having a circuit side (14), a backside (16), and a substrate contact (18) on the circuit side (14). The method also includes the steps of forming a substrate opening (30) from the backside (16) to the substrate contact (18), and then bonding the conductive interconnect (44) to an inner surface (32) of the substrate contact (18). A system (62) for performing the method includes the semiconductor substrate (12), a thinning system (64) for thinning the semiconductor substrate (12), an etching system (66A) for forming the substrate opening (30), and a bonding system (38) for bonding the conductive interconnect (44) to the substrate contact (18). The semiconductor component (50) can be used to form module components (98), underfilled components (106), stacked components (116), and image sensor semiconductor components (50IS).

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